

Please amend the Application as follows:

IN THE SPECIFICATION:

Please substitute the attached Substitute Specification and Abstract for the translation of this application. The Substitute Specification conforms to U.S. Practice and places the application in better English.

IN THE CLAIMS:

Cancel Claims 1 to 16.

Add claims 17 to 31 as follows:

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17. (New) Apparatus for handling wafers to place said wafers in a chamber having a wafer holding device including a cooling plate and a heating plate, wherein said wafers are provided for processing in said chamber in a wafer cassette, comprising:

an external handling device having grippers for transferring said wafers between said cassette and said chamber; and

an internal handling device provided in a cooled area of said chamber, said internal handling device having at least one fork arranged to move with at least two degrees of freedom and arranged to interact with said grippers of said external handling device to receive a wafer therefrom, said fork being arranged to move said wafers between said cooling plate and said heating plate.